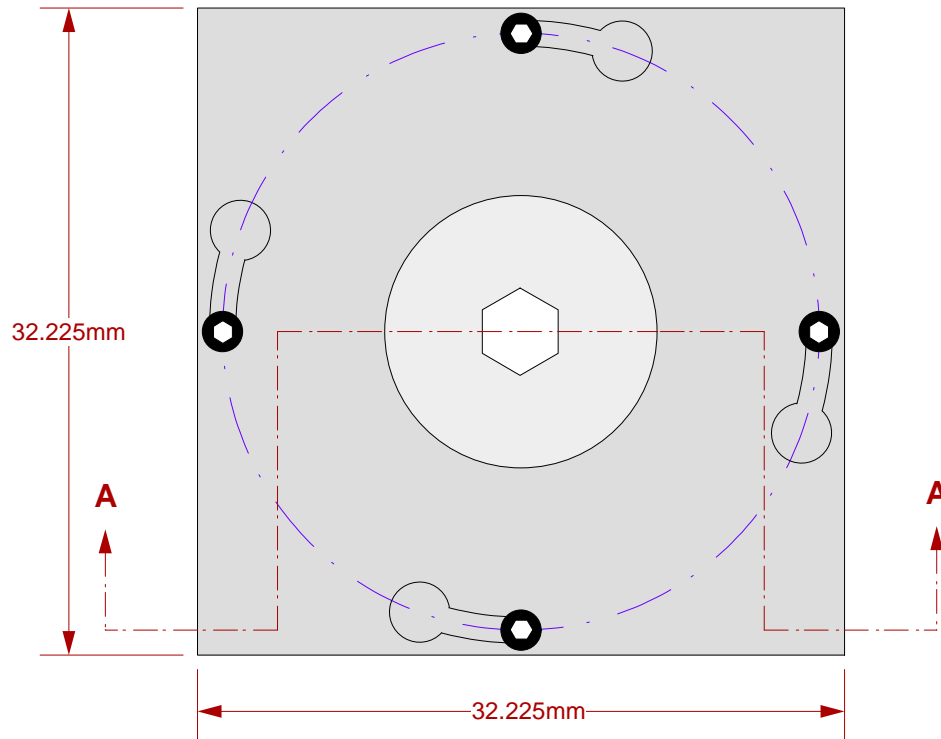


GHz BGA Socket - Direct mount, solderless

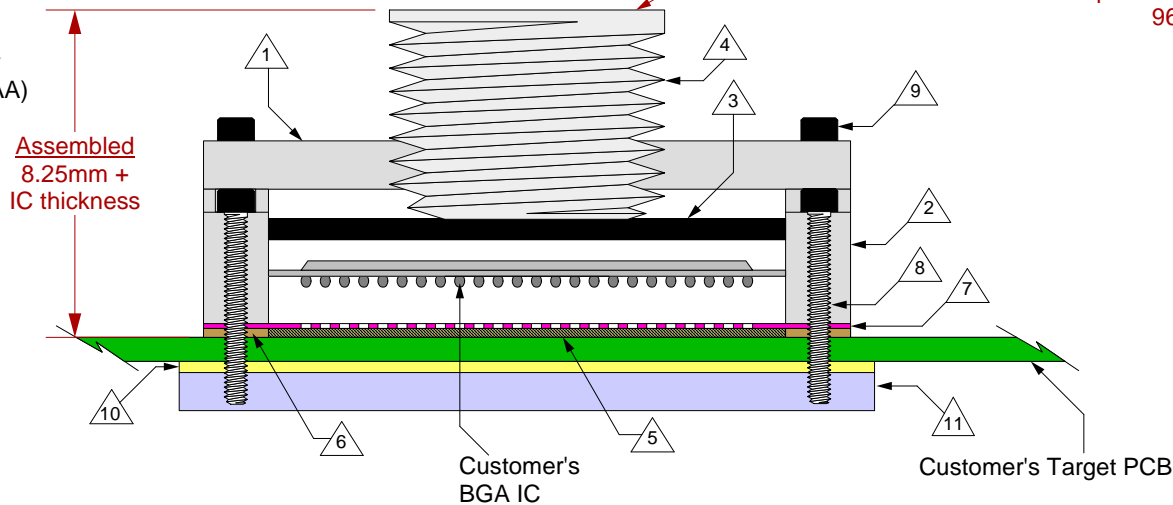
Top View




Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

Side View
(Section AA)

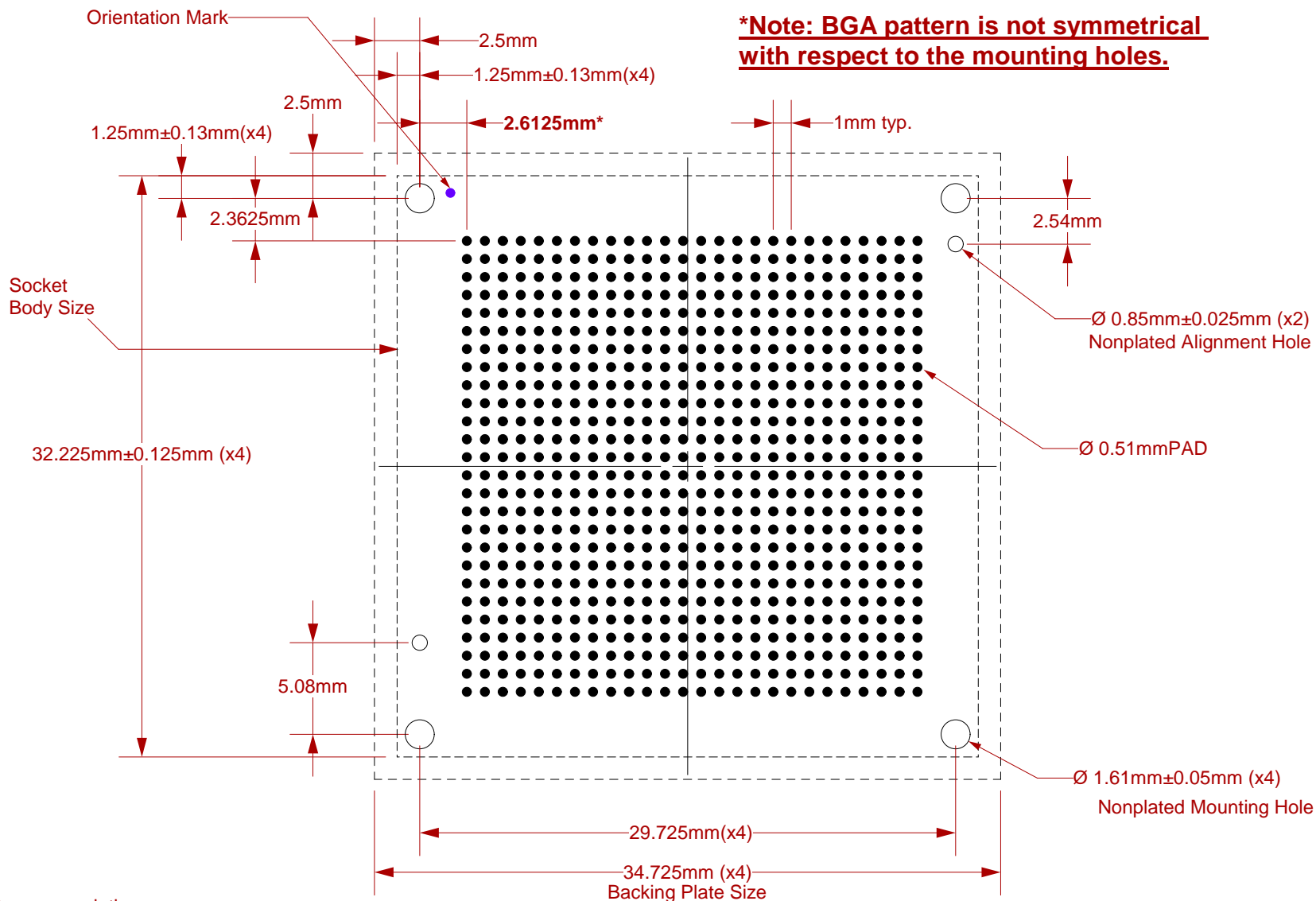


- | | |
|----|---|
| 1 | Socket Lid: Black anodized Aluminum.
Thickness = 2.5mm. |
| 2 | Socket base: Black anodized Aluminum.
Thickness = 6.5mm. |
| 3 | Compression Plate: Black anodized Aluminum.
Thickness = 2.5mm. |
| 4 | Compression screw: Clear anodized Aluminum.
Thickness = 5mm, Hex socket = 5mm. |
| 5 | Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle).
Thickness = 0.5mm. |
| 6 | Elastomer Guide: Non-clad FR4.
Thickness = 0.475mm. |
| 7 | Ball Guide: Kapton polyimide. |
| 8 | Socket base screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread, 9.52mm long. |
| 9 | Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread. |
| 10 | Insulation Plate: FR4/G10, 1.59mm thick. |
| 11 | Backing Plate: 6.5mm thick Aluminum. |

	SG-BGA-8012 Drawing © 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Status: Released	Scale: -	Rev: B
		Drawing: J. Glab	Date: 02/11/08	
		File: SG-BGA-8012 Dwg	Modified: 7/22/09, AE	

All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View



Target PCB Recommendations


Total thickness: 1.6mm min.

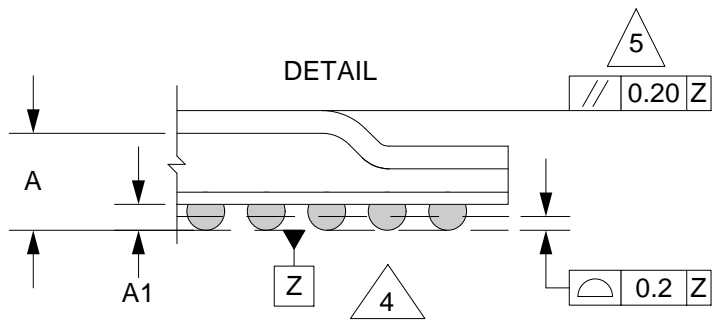
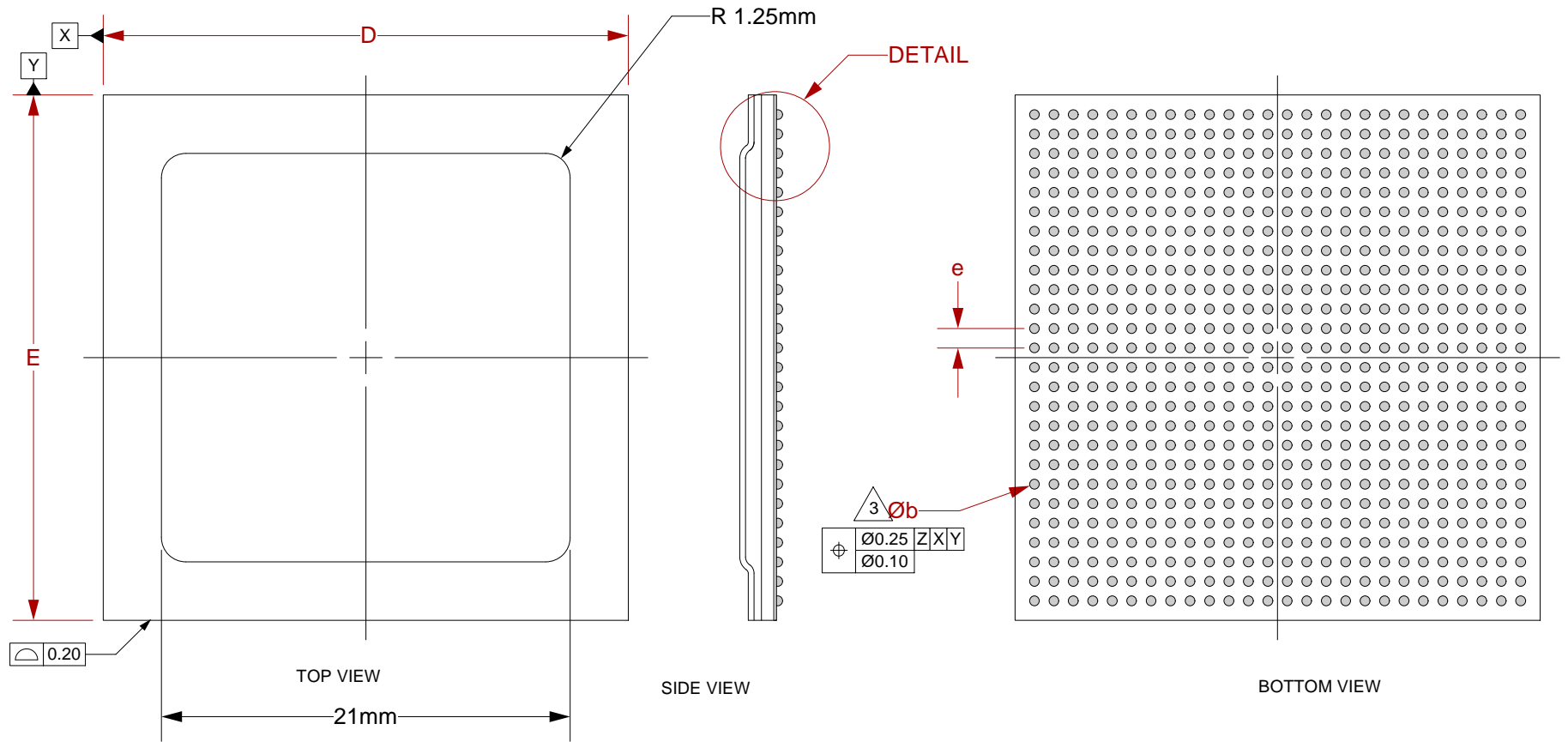
Plating: Gold or Solder finish

PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.


 <p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p>SG-BGA-8012 Drawing</p>		<p>Status: Released</p>	<p>Scale: -</p>	<p>Rev: B</p>
	<p>Drawing: J. Glab</p>			<p>Date: 02/11/08</p>	
	<p>File: SG-BGA-8012 Dwg</p>			<p>Modified: 7/22/09, AE</p>	



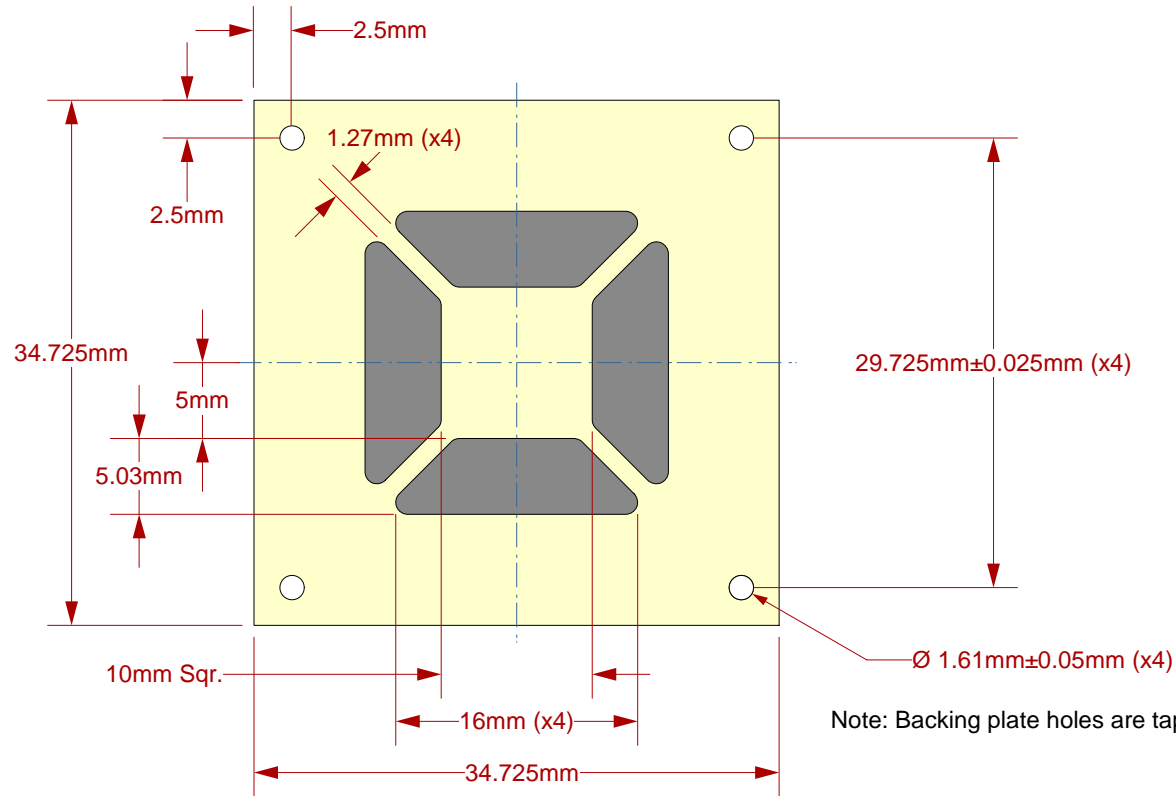
- 1 Dimensions are in millimeters.
- 2 Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		3.22
A1	0.4	0.6
b	0.5	0.70
D	27.00 BSC	
E	27.00 BSC	
e	1.0 BSC	

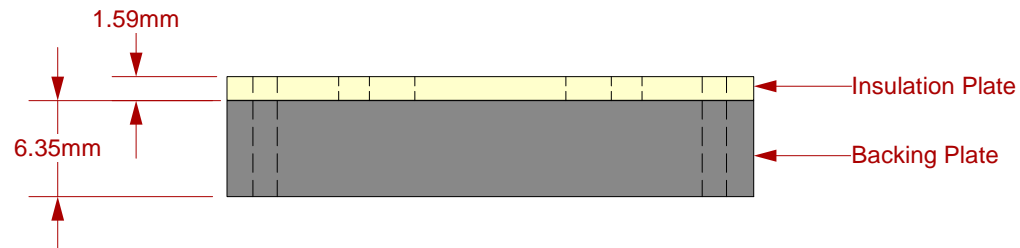
Array 26x26

	SG-BGA-8012 Drawing	Status: Released	Scale: -	Rev: B
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Top View



Side View



Description: Backing Plate with Insulation Plate

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	<p>Drawing: J. Glab</p>	<p>Date: 02/11/08</p>		
	<p>File: SG-BGA-8012 Dwg</p>	<p>Modified: 7/22/09, AE</p>		

All dimensions are in mm.
All tolerances are $\pm 0.125\text{mm}$.
(Unless stated otherwise)